

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **10-March-2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► Products affected:

Sales Name	SP N°	OPN	Package
IRF7580MTRPBF	SP001551448	IRF7580MTRPBF	DIRECTFET
IRF7780MTRPBF	SP001551498	IRF7780MTRPBF	DIRECTFET
IR38063MTRPBF	SP001531586	IR38063MTRPBF	PQFN 5X7 34L

► Detailed Change Information:

Subject: Transfer of wafer backend of line processing and wafer test from Infineon Newport, Wales to Infineon Kulim, Malaysia, Extension of PCN 1079

Reason: As part of a manufacturing consolidation plan announced in March 2015, Infineon indicated that it would be closing the Newport, Wales facility and transferring the production capability.

Description: Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

Wafer Backend Processing

	OLD	NEW
Site	Infineon Technologies Newport Limited	Infineon Technologies AG, Kulim, Malaysia

► Product Identification: Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► Impact of Change: No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► Attachments:

► Time Schedule:

- Final qualification report: Available
- First samples available: On Request
- Intended start of delivery: 22-March-2017

If you have any questions, please do not hesitate to contact your local Sales office.